



Physical Interfaces & Carriers Japan TC Chapter

Meeting Summary and Minutes

Japan Standards Spring 2021 Meetings

April 14, 2021, 9:00-12:00

SEMI Japan office, Tokyo, Japan

TC Chapter Announcements

Next TC Chapter Meeting

August 5th 9:00-12:00 (JST) @SEMI Japan Office Room2 and OVTCC

Table 1 Meeting Attendees

Italics indicate virtual participants

Co-Chairs: Tsuyoshi Nagashima (Miraial), Yasuhisa Ito (Murata Machinery), Daisuke Sado (DAIHEN)

SEMI Staff: Hirofumi Kanno (SEMI Japan)

<i>Company</i>	<i>Last</i>	<i>First</i>	<i>Company</i>	<i>Last</i>	<i>First</i>
Acteon NEXT	Komatsu	Shoji	<i>Sinfonia Technologies</i>	<i>Suzuki</i>	<i>Atsushi</i>
<i>Tokyo Electron</i>	<i>Mashiro</i>	<i>Supika</i>	<i>Marubeni Plax</i>	<i>Igeta</i>	<i>Luke</i>
<i>Inficon</i>	<i>Fukunaga</i>	<i>Tsukasa</i>	<i>DISCO</i>	<i>Kobinata</i>	<i>Ryosuke</i>
<i>DAIFUKU</i>	<i>Suzuki</i>	<i>Tomoko</i>	<i>Murata Machinery</i>	<i>Ito</i>	<i>Yasuhisa</i>
<i>DAIHEN</i>	<i>Sado</i>	<i>Daisuke</i>	<i>Shin-Etsu Polymer</i>	<i>Shida</i>	<i>Hiroyuki</i>
<i>Hirata Corporation</i>	<i>Toyoda</i>	<i>Noriyoshi</i>	<i>Sony Semiconductor Solutions</i>	<i>Goto</i>	<i>Hisashi</i>
<i>JEOL</i>	<i>Asayama</i>	<i>Kyoichiro</i>	<i>Miraial</i>	<i>Nagashima</i>	<i>Tsuyoshi</i>
<i>KOKUSAI ELECTRIC</i>	<i>Matsuda</i>	<i>Mitsuhiro</i>	<i>Tokyo Seimitsu</i>	<i>Taniguchi</i>	<i>Naomune</i>
			SEMI Japan	Kanno	Hirofumi

Table 2 Leadership Changes

None

Table 3 Committee Structure Changes

None

Table 4 Ballot Results

<i>Document #</i>	<i>Document Title</i>	<i>Committee Action</i>
6688	New Standard - SPECIFICATION FOR 300mm TAPE FRAME FOU P LOAD PORT	Passed , with technical changes, Ratification Ballot to be issued
6689	New Standard – SPECIFICATION FOR 300mm TAPE FRAME FOU P	Passed , with technical changes, Ratification Ballot to be issued

#1 **Passed** ballots and line items will be submitted to the ISC Audit & Review Subcommittee for procedural review.



#2 **Failed** ballots and line items were returned to the originating task forces for re-work and re-balloting or abandoning.

Table 5 Activities Approved by the GCS between meetings of the TC Chapter

None

Table 6 Authorized Activities

Listing of all revised or new SNARF(s) approved by the Originating TC Chapter.

#	Type	SC/TF/WG	Details
6750	SNARF	Panel Level Packaging (PLP) Panel FOUF Task Force	Line Item Revision to SEMI E181-0321 - SPECIFICATION FOR PANEL FOUF FOR PANEL LEVEL PACKAGING, SEMI E181.1-0321 - SPECIFICATION FOR PANEL FOUF FOR 510 mm – 515 mm PANEL SIZE and 12 SLOTS, SEMI E181.2-0321 - SPECIFICATION FOR PANEL FOUF FOR 510 mm – 515 mm PANEL SIZE and 6 SLOTS, SEMI E181.3-0321 - SPECIFICATION FOR PANEL FOUF FOR 600 mm – 600 mm PANEL SIZE and 12 SLOTS, and SEMI E181.4-0321 - SPECIFICATION FOR PANEL FOUF FOR 600 mm – 600 mm PANEL SIZE and 6 SLOTS
6751			Line Item Revision to SEMI E181.3-0321 - SPECIFICATION FOR PANEL FOUF FOR 600 mm – 600 mm PANEL SIZE and 12 SLOTS
6752			Line Item Revision to SEMI E181.4-0321 - SPECIFICATION FOR PANEL FOUF FOR 600 mm – 600 mm PANEL SIZE and 6 SLOTS

#1 SNARFs and TFOFs are available for review on the SEMI Web site at:

<http://downloads.semi.org/web/wstdsbal.nsf/TFOFSNARF>

Table 7 Authorized Ballots

#	Type	SC/TF/WG	Details
6750	Cycle 5	Panel Level Packaging (PLP) Panel FOUF Task Force	Line Item Revision to SEMI E181-0321 - SPECIFICATION FOR PANEL FOUF FOR PANEL LEVEL PACKAGING, SEMI E181.1-0321 - SPECIFICATION FOR PANEL FOUF FOR 510 mm – 515 mm PANEL SIZE and 12 SLOTS, SEMI E181.2-0321 - SPECIFICATION FOR PANEL FOUF FOR 510 mm – 515 mm PANEL SIZE and 6 SLOTS, SEMI E181.3-0321 - SPECIFICATION FOR PANEL FOUF FOR 600 mm – 600 mm PANEL SIZE and 12 SLOTS, and SEMI E181.4-0321 - SPECIFICATION FOR PANEL FOUF FOR 600 mm – 600 mm PANEL SIZE and 6 SLOTS
6751			Line Item Revision to SEMI E181.3-0321 - SPECIFICATION FOR PANEL FOUF FOR 600 mm – 600 mm PANEL SIZE and 12 SLOTS
6752			Line Item Revision to SEMI E181.4-0321 - SPECIFICATION FOR PANEL FOUF FOR 600 mm – 600 mm PANEL SIZE and 6 SLOTS

Table 8 SNARF(s) Granted a One-Year Extension

None

Table 9 SNARF(s) Abolished

None

Table 10 Standard(s) to receive Inactive Status

None

Table 11 New Action Items

<i>Item #</i>	<i>Assigned to</i>	<i>Details</i>
05102021-01	SEMI Japan Staff	Check TFOFs in 5.5, 5.6 and 5.7, 5.9, and request the TF leader to submit the report if it is clearly indicated in the Liaison destination.

Table 12 Previous Meeting Action Items

<i>Item #</i>	<i>Assigned to</i>	<i>Details</i>
20210118-1	Shoji Komatsu (Acteon NEXT)	PI&C NA TC Chapter does not have a Task Force to act as counterpart for Int'l 450mm Shipping Box TF, so the next Silicon Wafer Japan TC Chapter will decide whether to disband the TF. → Done
20210118-2	Hirofumi Kanno (SEMI Staff)	Confirm with PI&C NA TC Chapter that the Int'l 450mm Shipping Box TF has been officially disbanded. → Done
20210118-3	Supika Mashiro (Tokyo Electron)	Discuss future actions for SEMI E92-0302E (Reapproved 0615) by the next meeting. → Done. The PIC Maintenance Task Force will work on the revision of E92, since it was found by Supika Mashiro (Tokyo Electron) that it needs maintenance.

1 Welcome, Reminders, and Introductions

Daisuke Sado (DAIHEN) called the meeting to order at 9:00. The meeting reminders on antitrust issues, intellectual property issues and holding meetings with international attendance were reviewed. Attendees introduced themselves.

Attachment: 01SEMI Standards Required Elements_August2018_E+J

2 Review of Previous Meeting Minutes

The TC Chapter reviewed the minutes of the previous meeting held on September 20, 2019.

Motion:	Approve the previous meeting minutes as written
By / 2nd:	Tsuyoshi Nagashima (Miraial), / Shoji Komatsu (Acteon NEXT)
Discussion:	None
Vote:	10 in favor and 0 opposed. Motion passed.

Attachment: 02_20201222_PI&C-Japan_MeetingMinutes_v1

3 Liaison Reports

3.1 Physical Interfaces & Carriers North America TC Chapter

Hirofumi Kanno (SEMI) reported for the <Committee Name> Europe TC Chapter. Of note:

Attachment: 03_NA PIC Liaison Report Feb2021 v1

3.2 SEMI Staff Report

Hirofumi Kanno (SEMI) gave the SEMI Staff Report.

Attachment: 04 Staff Report March 2021_v1

4 Ballot Review

NOTE 1: TC Chapter adjudication on ballots reviewed is detailed in the Audits & Review (A&R) Subcommittee Forms for procedural review. The A&R forms are available as attachments to these minutes. The attachment number for each balloted document is provided under each ballot review section below.

<i>Document #</i>	<i>Document Title</i>	<i>Committee Action</i>
6688	New Standard: Specification for 300mm Tape Frame FOUP Load Port	Passed with technical changes. Ratification ballot will be issued. Attachment: 05_6688BallotReview
6689	New Standard: Specification for 300mm Tape Frame FOUP	Passed with technical changes. Ratification ballot will be issued. Attachment: 06_6689_BallotReview

5 Subcommittee and Task Force Reports

5.1 300 mm Tape Frame PI&C TF

Naomune Taniguchi (Tokyo Seimitsu) reported for the Task Force.

Attachment: 07 20210414_300mm Tape Frame PIC TF_ActivityReports

5.2 Global PIC Standards Maintenance TF

Shoji Komatsu (Acteon Next) reported for the Task Force.

5.3 Japan Electron Microscopy Workflow liaison TF

Kyoichiro Asayama (JEOL) reported for the Task Force.

5.4 Panel Level Packaging Panel FOUP TF

Shoji Komatsu (Acteon Next) reported for the Task Force.

Attachment: 08 Panel FOUP TF report_20210414

5.5 [Liaison: 3D Packaging & Integration JA TC Chapter] Panel Level Packaging Glass Carrier TF

5.6 [Liaison: 3D Packaging & Integration NA TC Chapter] Panel Level Packaging Panel TF

5.7 [Liaison: Silicon Wafer Japan TC Chapter] JA Shipping Box TF

5.8 [Liaison: Silicon Wafer Japan TC Chapter / PI&C TC NA TC Chapter] International 450mm Shipping Box

Shoji Komatsu (Acteon Next) reported that the 450mm Shipping Box TF was disbanded on the NA side, and the TF on the Japan side was also disbanded.

5.9 [Liaison: Traceability] Panel Level Packaging (PLP) Glass Carrier ID Marking TF

Action Item: 05102021-01, Check TFOFs in 5.5, 5.6 and 5.7, 5.9, and request the TF leader to submit the report if it is clearly indicated in the Liaison destination [SEMI Staff].

6 Old Business

6.1 Project Period Review

None

6.2 5 Year Review

Action will be taken at the next committee meeting.

7 New Business

7.1 Panel FOUP-TF will submit 3 SNARFs for E181 related line ballot (Cycle 5).

Motion: Approve the SNARF for Line Item Revision to SEMI E181-0321 - SPECIFICATION FOR PANEL FOUP FOR PANEL LEVEL PACKAGING, SEMI E181.1-0321 - SPECIFICATION FOR PANEL FOUP FOR 510 mm – 515 mm PANEL SIZE and 12 SLOTS, SEMI E181.2-0321 - SPECIFICATION FOR PANEL FOUP FOR 510 mm – 515 mm PANEL SIZE and 6 SLOTS, SEMI E181.3-0321 - SPECIFICATION FOR PANEL FOUP FOR 600 mm – 600 mm PANEL SIZE and 12 SLOTS, and SEMI E181.4-0321 - SPECIFICATION FOR PANEL FOUP FOR 600 mm – 600 mm PANEL SIZE and 6 SLOTS

By / 2nd: Shoji Komatsu / Acteon NEXT, Hiroyuki Shida / Shin-Etsu Polymer

Discussion: None

Vote: 11-0 Motion passed.

Attachment: 09 SNARF_E181_R0

Motion: Approve the SNARF Line Item Revision to SEMI E181.3-0321 - SPECIFICATION FOR PANEL FOUP FOR 600 mm – 600 mm PANEL SIZE and 12 SLOTS

By / 2nd: Shoji Komatsu / Acteon NEXT, Hiroyuki Shida / Shin-Etsu Polymer

Discussion: None

Vote: 11-0 Motion passed.

Attachment: 10_SNARF_E181.3_R0

Motion: Approve the SNARF Line Item Revision to SEMI E181.4-0321 - SPECIFICATION FOR PANEL FOUP FOR 600 mm – 600 mm PANEL SIZE and 6 SLOTS

By / 2nd: Shoji Komatsu / Acteon NEXT, Hiroyuki Shida / Shin-Etsu Polymer

Discussion: None

Vote: 11-0 Motion passed.

Attachment: 11_SNARF_E181.4_R0

Motion: Authorize the Three Documents for Letter Ballot on Cycle 5 - 2021

By / 2nd: Shoji Komatsu / Acteon NEXT, Hiroyuki Shida / Shin-Etsu Polymer

Discussion: None

Vote: 11-0 Motion passed.

7.2 Report of Ratification Ballots Result

7.3 Discussion on the technical reasons accompanying Disapprove Votes to the following ratification ballots if any



7.3.1 R6684 New Standard: SPECIFICATION FOR PANEL FOUP LOADPORT FOR PANEL LEVEL PACKAGING

Attachment: 12_Crystal Reports - CastBallotTally_1n2pic

Attachment: 13_R6684_Ballot Review_final

8 Next Meeting and Adjournment

The next meeting is scheduled for August 5th 9:00-12:00 (JST) @SEMI Japan Office Room2 and OVTCC. See <http://www.semi.org/standards-events> for the current list of events.

Adjournment: [12:00]>.

Respectfully submitted by:

Hirofumi Kanno

Manager

SEMI Japan

Phone: +81.3.3222.5863

Email: hkanno@semi.org

Minutes tentatively approved by:

Tsuyoshi Nagashima (Mirai), Co-chair	<Date approved>
Daisuke Sado (Daihen), Co-chair	<Date approved>
Ito Yasuhisa (Murata Machinery), Co-chair	

Table 13 Index of Available Attachments#1

<i>Title</i>	<i>Title</i>
01_RequiredElementNov2020Rev1-E&J-r1	02_20201222_PI&C-Japan_MeetingMinutes_v1
03_NA PIC Liaison Report Feb2021 v1	04 Staff Report March 2021_v1
05 6688_Ballot report template with Technical Change FINAL v2	06 6689_Ballot report template with Technical Change FINAL v2
07 20210414_300mm Tape Frame PIC TF_ActivityReports	08 Panel FOUP TF report_20210414
09 SNARF_E181_R0	10_SNARF_E181.3_R0
11_SNARF_E181.4_R0	12_Crystal Reports - CastBallotTally_1n2pic
13_R6684_Ballot Review_final	

#1 Due to file size and delivery issues, attachments must be downloaded separately. A .zip file containing all attachments for these minutes is available at www.semi.org. For additional information or to obtain individual attachments, please contact [SEMI Staff Name] at the contact information above.